SS1150 - SS1200

SURFACE MOUNT SCHOTTKY BARRIER DIODES

VOLTAGE RANGE: 150 - 200V
CURRENT: 1.0 A



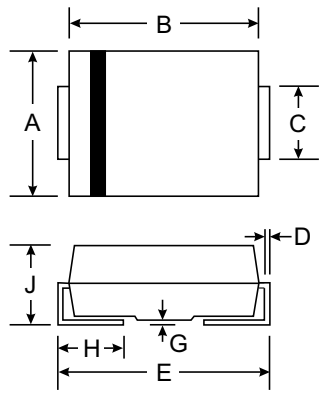
Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O

Mechanical Data

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)

RoHS COMPLIANT



SMA(DO-214AC)		
Dim	**Min**	**Max**
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SS1150	SS1200	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	150	200	Volts
Maximum RMS voltage	V_{RMS}	105	140	Volts
Maximum DC blocking voltage	V_{DC}	150	200	Volts
Maximum average forward rectified current at T_L(see fig.1)	$I_{(AV)}$	1.0		Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30.0		Amps
Maximum instantaneous forward voltage at 1.0A	V_F	0.85	0.95	Volts
Maximum DC reverse current T_A=25℃	I_R	0.2		mA
at rated DC blocking voltage T_A=100℃		2.0		
Typical junction capacitance (NOTE 1)	C_J	90		pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	88.0		°C/W
Operating junction temperature range	$T_{J,}$	-50 to +150		°C
Storage temperature range	T_{STG}	-50 to +150		°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES SS1150 THRU SS1200

FIG. 1- FORWARD CURRENT DERATING CURVE

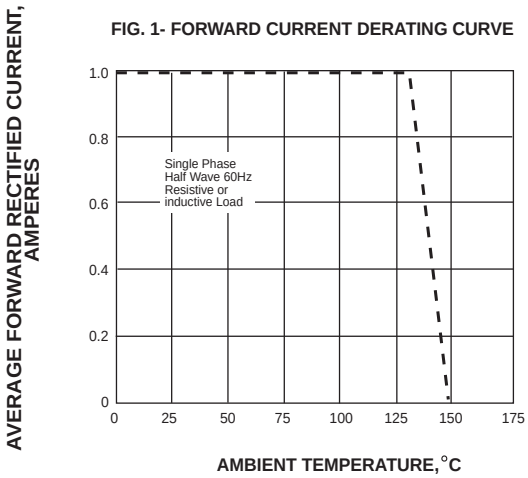


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

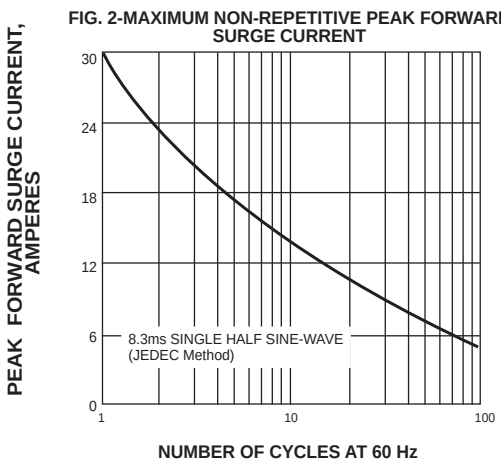


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

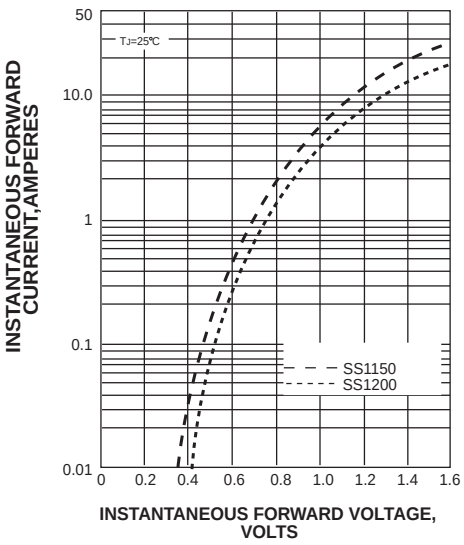


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

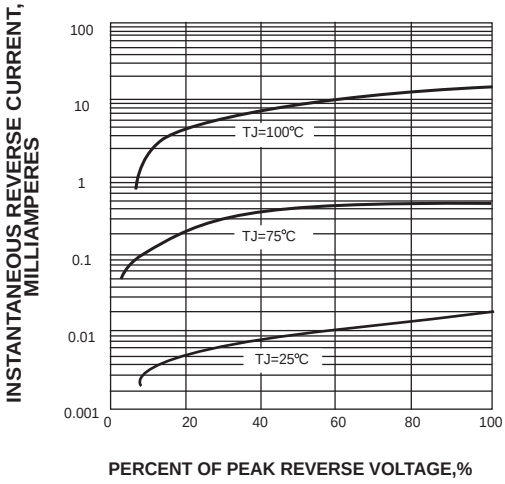


FIG. 5-TYPICAL JUNCTION CAPACITANCE

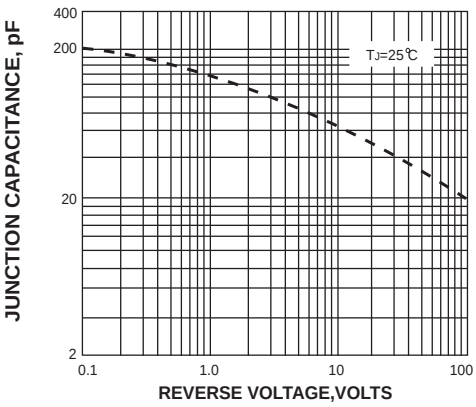


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

